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(54) **MANUFACTURING METHOD OF A
FLEXIBLE OLED DISPLAY PANEL**

(71) Applicant: **Wuhan China Star Optoelectronics
Semiconductor Display Technology
Co., Ltd., Wuhan, Hubei (CN)**

(72) Inventor: **Xia CHEN, Wuhan, Hubei (CN)**

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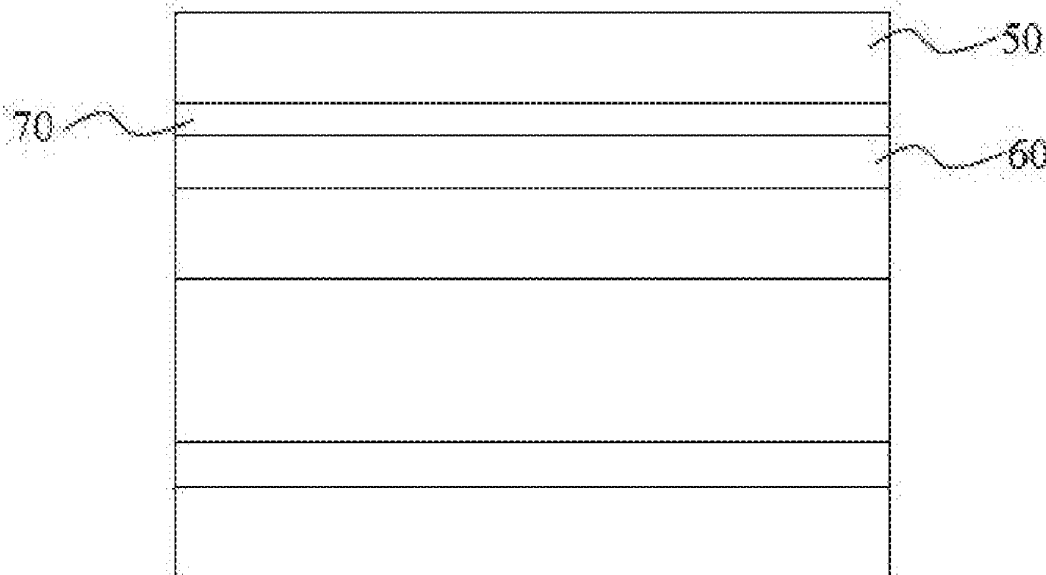
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51/0022 (2013.01)

(57)

ABSTRACT

The present disclosure discloses a manufacturing method of a flexible OLED display panel, including: providing a rigid substrate and forming a flexible substrate on the rigid substrate; forming a thin film transistor array layer on the flexible substrate; forming an OLED display unit on the thin film transistor array layer; forming an encapsulation layer on the OLED display unit; forming a protection cover on the encapsulation layer; and peeling the rigid substrate from the flexible substrate by using a laser lift-off process. The present disclosure is uses a coating process or a printing process to form each layer structure in a flexible OLED display panel. The manufacturing method effectively reduces the total thickness of the device and increases the adhesion between the layers so as to avoid the problem that the flexible OLED display panel is wrinkled or peeled when bent.



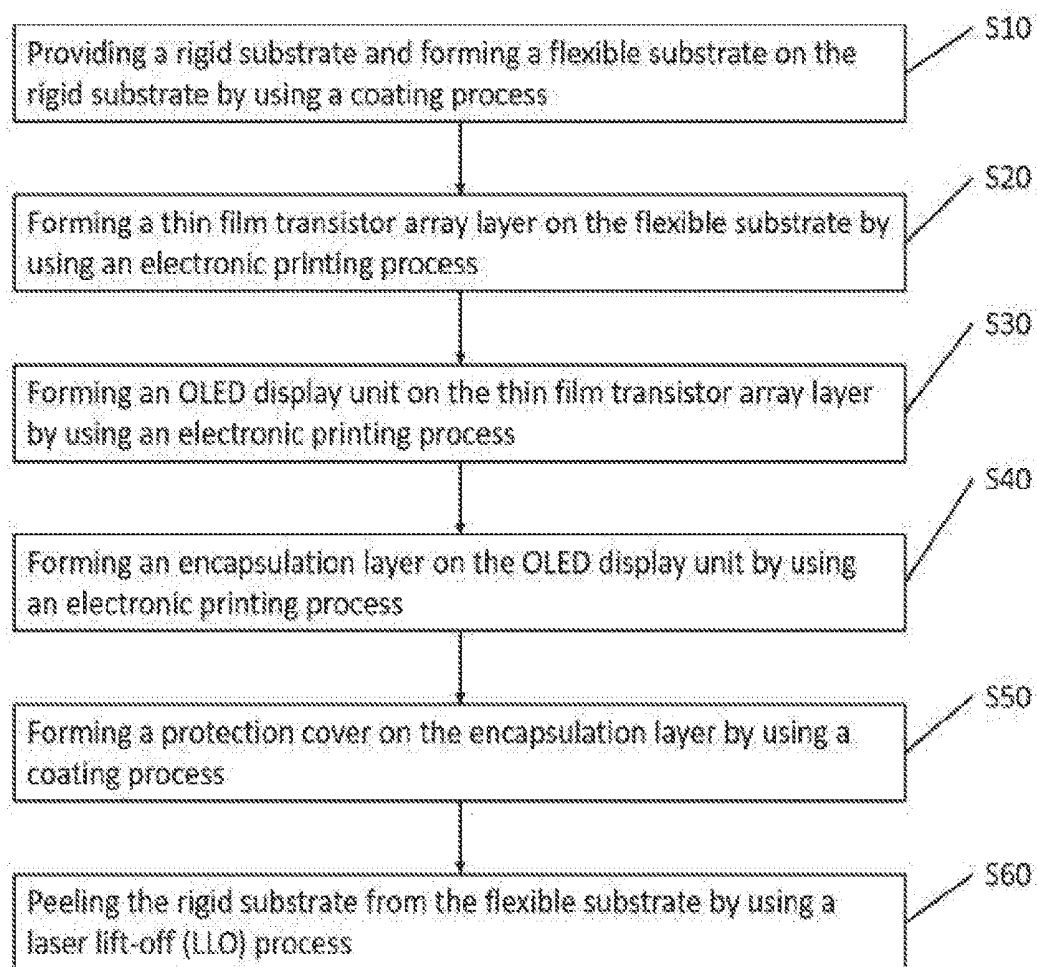


Fig. 1

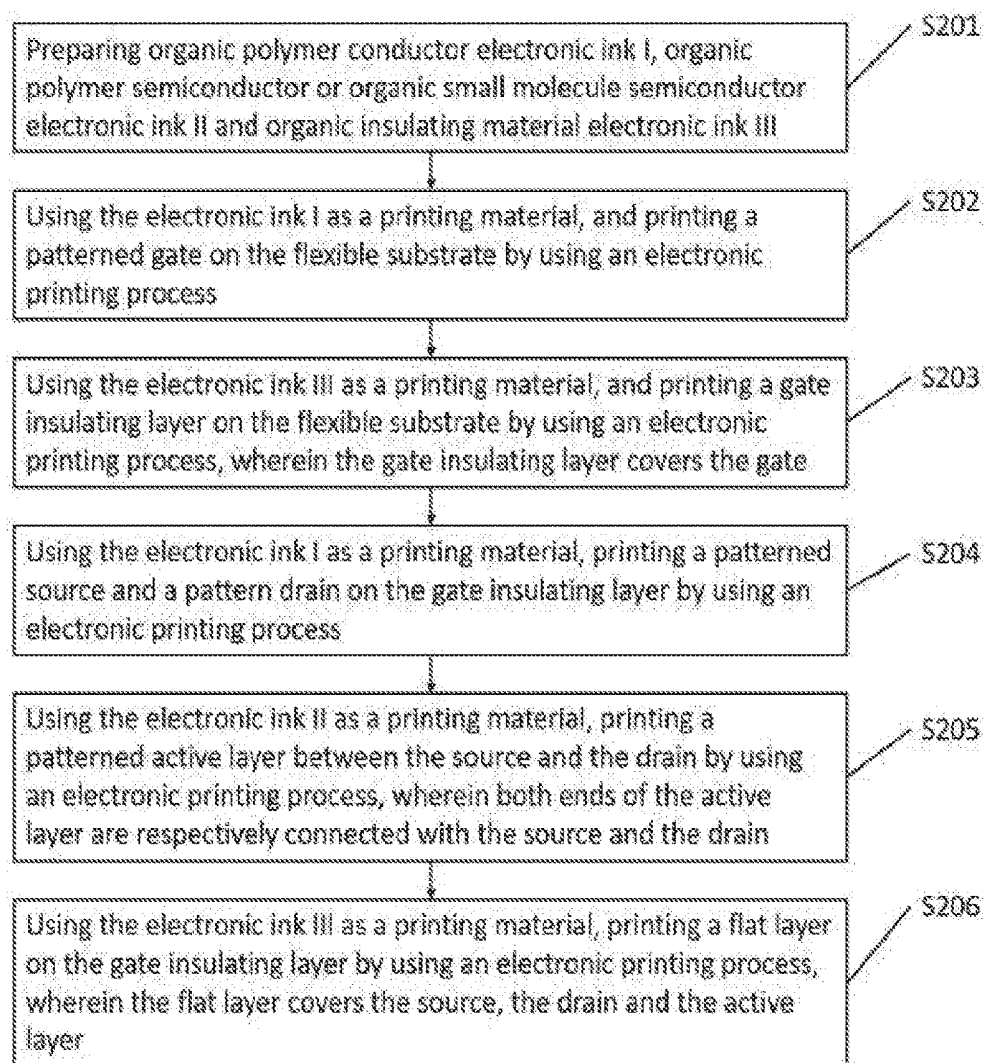


Fig. 2

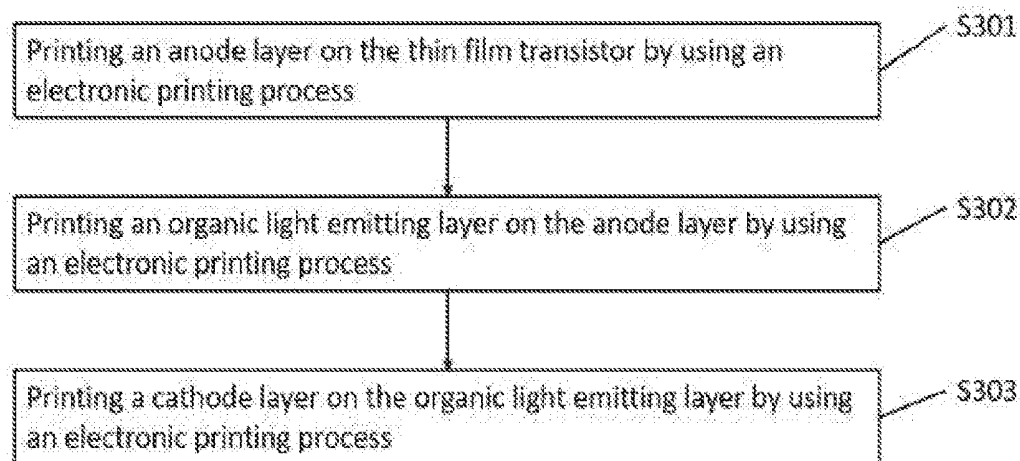


Fig. 3

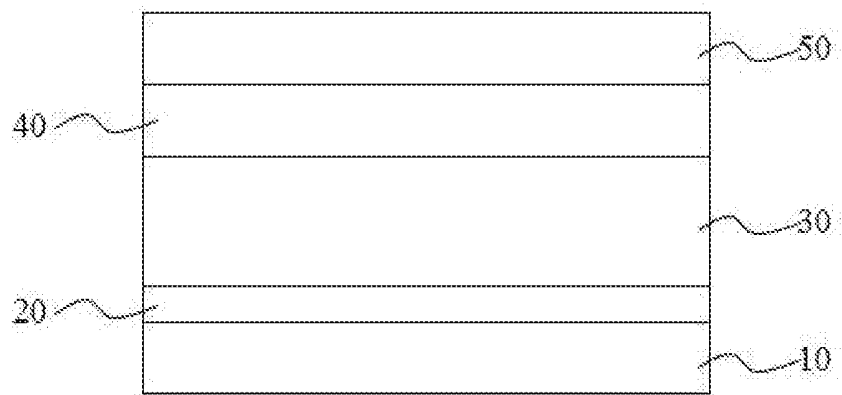


Fig. 4

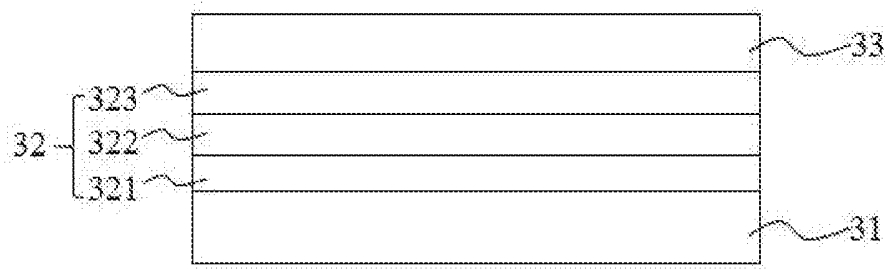


Fig. 5

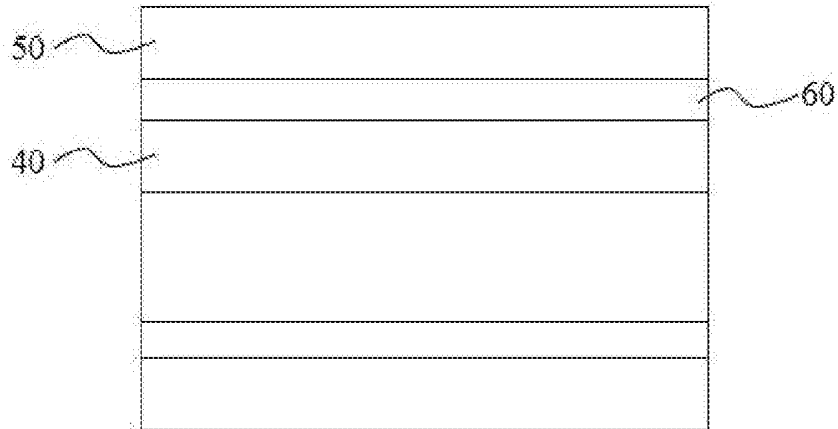


Fig. 6

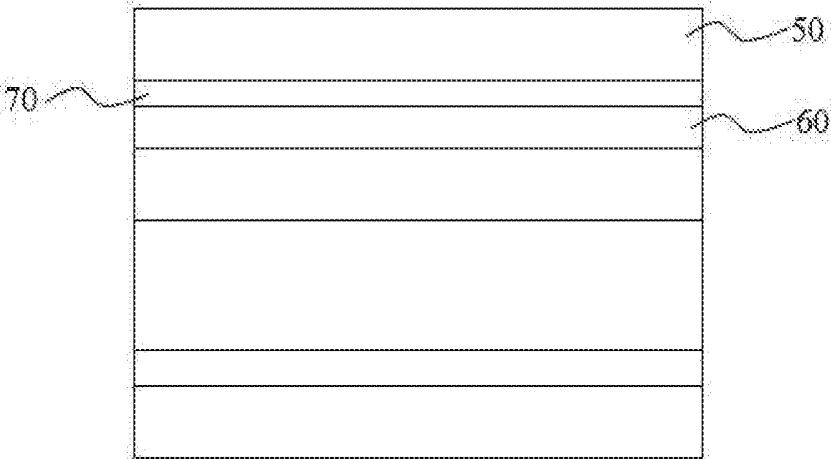


Fig. 7

MANUFACTURING METHOD OF A FLEXIBLE OLED DISPLAY PANEL

RELATED APPLICATIONS

[0001] The present application is a National Phase of International Application Number PCT/CN2017/113222, filed Nov. 28, 2017, and claims the priority of China Application No. 201711160769.X, filed Nov. 20, 2017.

FIELD OF THE DISCLOSURE

[0002] The present disclosure relates to a display technology field, and more particularly to a manufacturing method of a flexible OLED display panel.

BACKGROUND OF THE DISCLOSURE

[0003] Organic light-emitting diodes (OLED) display panel has advantages of self-luminous, high contrast, thin thickness, wide viewing angle and fast response, etc., is the representative of a new generation of flat panel display technology, more and more respected by the industry. The flexible OLED display panel is one of the important trends.

[0004] Flexible OLED display panels can not only be thinner and lighter in size, but also reduce power consumption, thereby helping to enhance the life of the corresponding product. Meanwhile, due to the bendability and flexibility of the flexible OLED display panel, the durability of the OLED display panel is also higher than the conventional hard display panel. Flexible OLED display panel can be widely used in a variety of products with display capabilities, such as can be used in tablets, TVs, mobile terminals and a variety of wearable devices.

[0005] Generally, a flexible OLED display panel includes a flexible substrate and a thin film transistor array layer, an OLED display unit, an encapsulation layer, and a protection cover formed on the flexible substrate. In some aspects, a functional structure layer such as a touch structure layer and a polarizer is further arranged between the encapsulation layer and the protection cover. In an existing manufacturing process of a flexible OLED display panel, the thin film transistor array layer is usually formed by using a deposition film combined with a photolithography process to form a patterned device structure. The process thereof is not only energy consuming but also costly. The functional structure layers on the encapsulation layer, such as the protection cover, the touch structure layer and the polarizer, are usually attached to the encapsulation layer sequentially by using OCA optical glue. The total thickness of the flexible OLED display panel obtained by the preparation is relatively large, which is unfavorable to the light and thin development of the display panel. And in the way of attaching by the OCA optical glue, the adhesion between the layers is relatively small, so that the problem of wrinkles or peeling easily occurs during bending.

SUMMARY OF THE DISCLOSURE

[0006] In view of this, the present disclosure provides a manufacturing method of a flexible OLED display panel, the manufacturing method can effectively reduce the total thickness of the device and increase the adhesion between the layers so as to avoid the problem that the flexible OLED display panel is wrinkled or peeled when bent.

[0007] In order to achieve the above object, the present disclosure adopts the following technical solutions:

[0008] a manufacturing method of a flexible OLED display panel, wherein the flexible OLED display panel includes a thin film transistor array layer, an OLED display unit, an encapsulation layer and a protection cover sequentially formed on a flexible substrate, and the manufacturing method includes:

[0009] providing a rigid substrate and forming a flexible substrate on the rigid substrate by using a coating process;

[0010] forming a thin film transistor array layer on the flexible substrate by using an electronic printing process;

[0011] forming an OLED display unit on the thin film transistor array layer by using an electronic printing process;

[0012] forming an encapsulation layer on the OLED display unit by using an electronic printing process;

[0013] forming a protection cover on the encapsulation layer by using a coating process; and

[0014] peeling the rigid substrate from the flexible substrate by using a laser lift-off process.

[0015] Wherein the step of forming a thin film transistor array layer by using an electronic printing process specifically includes: patterning a gate on the flexible substrate by using an electronic printing process; printing a gate insulating layer on the flexible substrate by using an electronic printing process, wherein the gate insulating layer covers the gate; patterning a source and a drain on the gate insulating layer by using an electronic printing process; printing a patterned active layer between the source and the drain by using an electronic printing process, wherein both ends of the active layer are respectively connected with the source and the drain; and printing a flat layer on the gate insulating layer by using an electronic printing process, wherein the flat layer covers the source, the drain and the active layer.

[0016] Wherein the step of forming an OLED display unit by using an electronic printing process specifically includes: printing an anode layer on the thin film transistor by using an electronic printing process; printing an organic light emitting layer on the anode layer by using an electronic printing process; and printing a cathode layer on the organic light emitting layer by using an electronic printing process.

[0017] Wherein the organic light emitting layer includes a hole transport functional layer, a light emitting material layer and an electron transport functional layer sequentially formed on the anode layer.

[0018] A touch structure layer is further arranged between the encapsulation layer and the protection cover; wherein, forming the touch structure layer on the encapsulation layer by using an electronic printing process.

[0019] Wherein a nano-silver electronic ink is used as a printing material, and a touch electrode and an electrode lead of the touch structure layer are printed on the encapsulation layer by using an electronic printing process.

[0020] A polarizer is further arranged between the touch structure layer and the protection cover; wherein forming the polarizer on the touch structure layer by using a coating process.

[0021] Wherein the coating process is a slit coating process or a spin-coating process or a spraying process.

[0022] Wherein the electronic printing process is an ink-jet printing process or a screen printing process

[0023] Wherein material of the flexible substrate is polyimide, polycarbonate, polyethersulfone, polyethylene terephthalate, polyethylene naphthalate, polyarylate or glass fiber reinforced plastic.

[0024] The manufacturing method of a flexible OLED display panel provided by the present disclosure is uses a coating process or a printing process to form each layer structure in a flexible OLED display panel. The manufacturing method effectively reduces the total thickness of the device and increases the adhesion between the layers so as to avoid the problem that the flexible OLED display panel is wrinkled or peeled when bent.

BRIEF DESCRIPTION OF THE DRAWINGS

[0025] FIG. 1 is a flowchart of a manufacturing method of a flexible OLED display panel according to an embodiment of the present disclosure;

[0026] FIG. 2 is a flowchart of a process of forming a thin film transistor array layer according to an embodiment of the present disclosure;

[0027] FIG. 3 is a flowchart of a process of forming an OLED display unit according to an embodiment of the present disclosure;

[0028] FIG. 4 is a schematic structural diagram of an OLED display panel formed according to an embodiment of the present disclosure;

[0029] FIG. 5 is a schematic structural diagram of an OLED display unit according to an embodiment of the present disclosure;

[0030] FIG. 6 is a schematic structural diagram of another OLED display panel formed according to an embodiment of the present disclosure;

[0031] FIG. 7 is a schematic structural diagram of another OLED display panel formed according to an embodiment of the present disclosure.

DETAILED DESCRIPTION OF PREFERRED EMBODIMENTS

[0032] To make the objectives, technical solutions, and advantages of the present disclosure clearer, the following describes the specific implementation manners of the present disclosure in detail with reference to the accompanying drawings. Examples of these preferred embodiments are illustrated in the drawings. The embodiments of the present disclosure shown in the drawings and described in the drawings are merely exemplary and the present disclosure is not limited to these embodiments.

[0033] Here, it should also be noted that, in order to avoid obscuring the present disclosure with unnecessary detail, only the structures and/or processing steps that are closely related to the solution according to the present disclosure are shown in the drawings, and other details of the present disclosure less concerned are omitted.

[0034] The present embodiment provides a manufacturing method of a flexible OLED display panel, referring to FIG. 1, the manufacturing method includes the steps of:

[0035] S10, providing a rigid substrate and forming a flexible substrate on the rigid substrate by using a coating process. Wherein the rigid substrate is selected as a glass substrate. Material of the flexible substrate may be polyimide (PI), polycarbonate (PC), polyethersulfone (PES), polyethylene terephthalate (PET), polyethylene naphthalate (PEN), polyarylate (PAR) or glass fiber reinforced plastic (FRP) and other polymer materials. The coating process can be selected as a slit coating process or a spin-coating process or a spraying process. In this embodiment, a slit coating process is preferably used.

[0036] S20, forming a thin film transistor array layer on the flexible substrate by using an electronic printing process. Referring to FIG. 2, the step specifically includes:

[0037] S201, preparing organic polymer conductor electronic ink I, organic polymer semiconductor or organic small molecule semiconductor electronic ink II and organic insulating material electronic ink III.

[0038] S202, using the electronic ink I as a printing material, and printing a patterned gate on the flexible substrate by using an electronic printing process.

[0039] S203, using the electronic ink III as a printing material, and printing a gate insulating layer on the flexible substrate by using an electronic printing process, wherein the gate insulating layer covers the gate.

[0040] S204, using the electronic ink I as a printing material, printing a patterned source and a pattern drain on the gate insulating layer by using an electronic printing process.

[0041] S205, using the electronic ink II as a printing material, printing a patterned active layer between the source and the drain by using an electronic printing process, wherein both ends of the active layer are respectively connected with the source and the drain.

[0042] S206, using the electronic ink III as a printing material, printing a flat layer on the gate insulating layer by using an electronic printing process, wherein the flat layer covers the source, the drain and the active layer.

[0043] In the step S20, the electronic printing process can be selected as an ink-jet printing process or a screen printing process, preferably using an ink-jet printing process. Compared with the prior art method of using the deposition thin film combined with the photolithography process, the method of forming a thin film transistor array layer by the electronic printing process can reduce the process difficulty and also reduce the thickness of the thin film transistor array layer, which further facilitates the light and thin development of the display panel.

[0044] S30, forming an OLED display unit on the thin film transistor array layer by using an electronic printing process. Referring to FIG. 3, the step specifically includes:

[0045] S301, printing an anode layer on the thin film transistor by using an electronic printing process.

[0046] S302, printing an organic light emitting layer on the anode layer by using an electronic printing process.

[0047] S303, printing a cathode layer on the organic light emitting layer by using an electronic printing process.

[0048] In the step S30, the electronic printing process can be selected as an ink-jet printing process or a screen printing process, preferably using an ink-jet printing process.

[0049] S40, forming an encapsulation layer on the OLED display unit by using an electronic printing process. Wherein the electronic printing process can be selected as an ink-jet printing process or a screen printing process, preferably using an ink-jet printing process.

[0050] S50, forming a protection cover on the encapsulation layer by using a coating process. Wherein the coating process can be selected as a slit coating process or a spin-coating process or a spraying process. In this embodiment, a spin-coating process is preferably used. The use of a coating process to form a protection cover provides a greater degree of cohesion of the protection cover and reduces the thickness of the device as compared to using an OCA optical adhesive.

[0051] S60, peeling the rigid substrate from the flexible substrate by using a laser lift-off (LLO) process.

[0052] In the above manufacturing method of a flexible OLED display panel, each layer structure in the flexible OLED display panel is formed by coating or printing process, the formed flexible OLED display panel is shown in FIG. 4. The flexible OLED display panel includes a thin film transistor array layer 20, an OLED display unit 30, an encapsulation layer 40 and a protection cover 50 sequentially formed on a flexible substrate 10. As shown in FIG. 5, the OLED display unit 30 includes an anode layer 31, an organic light emitting layer 32 and a cathode layer 33 sequentially formed on the thin film transistor array layer 20. The organic light emitting layer 32 includes a hole transport layer (HTL) 321, an emissive layer (EML) 322 and an electron transport layer (ETL) 323 prepared by organic materials.

[0053] In another preferred embodiment as shown in FIG. 6. In the flexible OLED display panel, a touch structure layer 60 is further arranged between the encapsulation layer 40 and the protection cover 50. Therefore, in the manufacturing method corresponding to the flexible OLED display panel provided in the foregoing embodiment, further includes steps between step S40 and step S50:

[0054] S40-1, forming a touch structure layer on the encapsulation layer by using an electronic printing process. Wherein a nano-silver electronic ink is used as a printing material, and a touch electrode and an electrode lead of the touch structure layer are printed on the encapsulation layer by using an electronic printing process. Wherein the electronic printing process may be selected as an ink-jet printing process or a screen printing process, preferably using a screen printing process. The use of an electronic printing process to form a touch structure layer provides a greater degree of cohesion of the touch structure layer and reduces the thickness of the device as compared to using an OCA optical adhesive.

[0055] Further, in another preferred embodiment as shown in FIG. 7. In the flexible OLED display panel, a polarizer 70 is further arranged between the touch structure layer 60 and the protection cover 50. Therefore, in the manufacturing method corresponding to the flexible OLED display panel provided in the foregoing embodiment, further includes steps between step S40-1 and step S50:

[0056] S40-2, forming a polarizer on the touch structure layer by using a coating process. Wherein the coating process can be selected as a slit coating process or a spin-coating process or a spraying process. In this embodiment, a slit coating process is preferably used. The use of a coating process to form a polarizer provides a greater degree of cohesion of the polarizer and reduces the thickness of the device as compared to using an OCA optical adhesive.

[0057] In summary, the manufacturing method of a flexible OLED display panel provided by the present disclosure uses a coating process or a printing process to form each layer structure in a flexible OLED display panel. The manufacturing method effectively reduces the total thickness of the device and increases the adhesion between the layers so as to avoid the problem that the flexible OLED display panel is wrinkled or peeled when bent.

[0058] It should be noted that, in this article, relational terms such as first and second and the like are merely used to distinguish one entity or operation from another, not necessarily require or imply any actual relationship or order

between such entities or operations. Moreover, the terms “including”, “comprising” or any other variation thereof, are intended to cover a non-exclusive inclusion such that a process, method, article, or apparatus that includes a list of elements include not only those elements, but also include other elements not expressly listed or also include elements inherent to the process, method, article, or device. Without further limitations, an element limited by the statement “including a . . .” does not exclude the existence of additional identical elements in the process, method, article, or apparatus that includes the element.

[0059] The foregoing descriptions are merely specific implementation manners of the present application. It should be noted that, for those skilled in the art, several improvements and modifications can be made without departing from the principle of the present disclosure, and these improvements and modifications should also be considered as the protection scope of the present application.

What is claimed is:

1. A manufacturing method of a flexible OLED display panel, wherein the flexible OLED display panel comprises a thin film transistor array layer, an OLED display unit, an encapsulation layer and a protection cover sequentially formed on a flexible substrate, and the manufacturing method comprises:

providing a rigid substrate and forming a flexible substrate on the rigid substrate by using a coating process; forming a thin film transistor array layer on the flexible substrate by using an electronic printing process; forming an OLED display unit on the thin film transistor array layer by using an electronic printing process; forming an encapsulation layer on the OLED display unit by using an electronic printing process; forming a protection cover on the encapsulation layer by using a coating process; and peeling the rigid substrate from the flexible substrate by using a laser lift-off process.

2. The manufacturing method of a flexible OLED display panel according to claim 1, wherein the step of forming a thin film transistor array layer by using an electronic printing process specifically comprises:

patterned a gate on the flexible substrate by using an electronic printing process; printing a gate insulating layer on the flexible substrate by using an electronic printing process, wherein the gate insulating layer covers the gate; patterning a source and a drain on the gate insulating layer by using an electronic printing process; printing a patterned active layer between the source and the drain by using an electronic printing process, wherein both ends of the active layer are respectively connected with the source and the drain; and printing a flat layer on the gate insulating layer by using an electronic printing process, wherein the flat layer covers the source, the drain and the active layer.

3. The manufacturing method of a flexible OLED display panel according to claim 1, wherein the step of forming an OLED display unit by using an electronic printing process specifically comprises:

printing an anode layer on the thin film transistor by using an electronic printing process; printing an organic light emitting layer on the anode layer by using an electronic printing process; and

printing a cathode layer on the organic light emitting layer by using an electronic printing process.

4. The manufacturing method of a flexible OLED display panel according to claim 3, wherein the organic light emitting layer comprises a hole transport functional layer, a light emitting material layer and an electron transport functional layer sequentially formed on the anode layer.

5. The manufacturing method of a flexible OLED display panel according to claim 1, wherein the coating process is a slit coating process or a spin-coating process or a spraying process; and the electronic printing process is an ink-jet printing process or a screen printing process.

6. The manufacturing method of a flexible OLED display panel according to claim 1, wherein material of the flexible substrate is polyimide, polycarbonate, polyethersulfone, polyethylene terephthalate, polyethylene naphthalate, polyarylate or glass fiber reinforced plastic.

7. A manufacturing method of a flexible OLED display panel, wherein the flexible OLED display panel comprises a thin film transistor array layer, an OLED display unit, an encapsulation layer, a touch structure layer and a protection cover sequentially formed on a flexible substrate, and the manufacturing method comprises:

providing a rigid substrate and forming a flexible substrate on the rigid substrate by using a coating process; forming a thin film transistor array layer on the flexible substrate by using an electronic printing process; forming an OLED display unit on the thin film transistor array layer by using an electronic printing process; forming an encapsulation layer on the OLED display unit by using an electronic printing process; forming a touch structure layer on the encapsulation layer by using an electronic printing process; forming a protection cover on the touch structure layer by using a coating process; and peeling the rigid substrate from the flexible substrate by using a laser lift-off process.

8. The manufacturing method of a flexible OLED display panel according to claim 7, wherein a nano-silver electronic ink is used as a printing material, and a touch electrode and an electrode lead of the touch structure layer are printed on the encapsulation layer by using an electronic printing process.

9. The manufacturing method of a flexible OLED display panel according to claim 7, wherein the step of forming a thin film transistor array layer by using an electronic printing process specifically comprises:

patterning a gate on the flexible substrate by using an electronic printing process; printing a gate insulating layer on the flexible substrate by using an electronic printing process, wherein the gate insulating layer covers the gate; patterning a source and a drain on the gate insulating layer by using an electronic printing process; printing a patterned active layer between the source and the drain by using an electronic printing process, wherein both ends of the active layer are respectively connected with the source and the drain; and printing a flat layer on the gate insulating layer by using an electronic printing process, wherein the flat layer covers the source, the drain and the active layer.

10. The manufacturing method of a flexible OLED display panel according to claim 7, wherein the step of forming

an OLED display unit by using an electronic printing process specifically comprises:

printing an anode layer on the thin film transistor by using an electronic printing process; printing an organic light emitting layer on the anode layer by using an electronic printing process; and printing a cathode layer on the organic light emitting layer by using an electronic printing process.

11. The manufacturing method of a flexible OLED display panel according to claim 10, wherein the organic light emitting layer comprises a hole transport functional layer, a light emitting material layer and an electron transport functional layer sequentially formed on the anode layer.

12. The manufacturing method of a flexible OLED display panel according to claim 7, wherein the coating process is a slit coating process or a spin-coating process or a spraying process; and the electronic printing process is an ink-jet printing process or a screen printing process.

13. The manufacturing method of a flexible OLED display panel according to claim 7, wherein material of the flexible substrate is polyimide, polycarbonate, polyethersulfone, polyethylene terephthalate, polyethylene naphthalate, polyarylate or glass fiber reinforced plastic.

14. A manufacturing method of a flexible OLED display panel, wherein the flexible OLED display panel comprises a thin film transistor array layer, an OLED display unit, an encapsulation layer, a touch structure layer, a polarizer and a protection cover sequentially formed on a flexible substrate, and the manufacturing method comprises:

providing a rigid substrate and forming a flexible substrate on the rigid substrate by using a coating process; forming a thin film transistor array layer on the flexible substrate by using an electronic printing process; forming an OLED display unit on the thin film transistor array layer by using an electronic printing process; forming an encapsulation layer on the OLED display unit by using an electronic printing process; forming a touch structure layer on the encapsulation layer by using an electronic printing process; forming a polarizer on the touch structure layer by using a coating process; forming a protection cover on the polarizer by using a coating process; and peeling the rigid substrate from the flexible substrate by using a laser lift-off process.

15. The manufacturing method of a flexible OLED display panel according to claim 14, wherein a nano-silver electronic ink is used as a printing material, and a touch electrode and an electrode lead of the touch structure layer are printed on the encapsulation layer by using an electronic printing process.

16. The manufacturing method of a flexible OLED display panel according to claim 14, wherein the step of forming a thin film transistor array layer by using an electronic printing process specifically comprises:

patterning a gate on the flexible substrate by using an electronic printing process; printing a gate insulating layer on the flexible substrate by using an electronic printing process, wherein the gate insulating layer covers the gate; patterning a source and a drain on the gate insulating layer by using an electronic printing process; printing a patterned active layer between the source and the drain by using an electronic printing process,

wherein both ends of the active layer are respectively connected with the source and the drain; and
printing a flat layer on the gate insulating layer by using an electronic printing process, wherein the flat layer covers the source, the drain and the active layer.

17. The manufacturing method of a flexible OLED display panel according to claim 14, wherein the step of forming an OLED display unit by using an electronic printing process specifically comprises:

printing an anode layer on the thin film transistor by using an electronic printing process;
printing an organic light emitting layer on the anode layer by using an electronic printing process; and
printing a cathode layer on the organic light emitting layer by using an electronic printing process.

18. The manufacturing method of a flexible OLED display panel according to claim 17, wherein the organic light emitting layer comprises a hole transport functional layer, a light emitting material layer and an electron transport functional layer sequentially formed on the anode layer.

19. The manufacturing method of a flexible OLED display panel according to claim 14, wherein the coating process is a slit coating process or a spin-coating process or a spraying process; and the electronic printing process is an ink-jet printing process or a screen printing process.

20. The manufacturing method of a flexible OLED display panel according to claim 14, wherein material of the flexible substrate is polyimide, polycarbonate, polyethersulfone, polyethylene terephthalate, polyethylene naphthalate, polyarylate or glass fiber reinforced plastic.

* * * * *

专利名称(译)	柔性OLED显示面板的制造方法		
公开(公告)号	US20190198584A1	公开(公告)日	2019-06-27
申请号	US15/578698	申请日	2017-11-28
[标]发明人	CHEN XIA		
发明人	CHEN, XIA		
IPC分类号	H01L27/32 H01L51/52 H01L51/00 H01L51/56		
CPC分类号	H01L27/3244 H01L51/5253 H01L51/0097 H01L51/56 H01L51/003 H01L51/0022 H01L51/0004 H01L27/323 H01L2251/5338 H01L2227/323 H01L2227/326 H01L27/1262 H01L51/5056 H01L51/5072 H01L27/127 H01L51/5206 H01L51/5221 H01L51/5012 G09F9/301 H01L51/5237 H01L27/1218 H01L27/1292		
优先权	201711160769.X 2017-11-20 CN		
其他公开文献	US10622417		
外部链接	Espacenet USPTO		

摘要(译)

本发明公开了一种柔性OLED显示面板的制造方法，包括：提供刚性基板，并在刚性基板上形成柔性基板；在柔性基板上形成薄膜晶体管阵列层；在薄膜晶体管阵列层上形成OLED显示单元；在OLED显示单元上形成封装层；在封装层上形成保护盖；并且通过使用激光剥离工艺从柔性基板上剥离刚性基板。本公开使用涂覆工艺或印刷工艺在柔性OLED显示面板中形成每个层结构。该制造方法有效地减小了器件的总厚度并增加了各层之间的粘附力，从而避免了柔性OLED显示面板在弯曲时起皱或剥落的问题。

